

Application Serial No.: 10/780,932

In the Specification

Please substitute the following amended paragraph for the paragraph beginning on page 9, line 26:

The ITO layer 360 is then etched using the patterned photoresist layer 372 as a mask. The ITO layer 360 can be etched utilizing wet etching with oxalic acid solution as an etchant. After the photoresist 372 is removed, ITO wiring 363 is formed, comprising ITO electrodes 361 and 362 to connect the metal lines 310 and 330. However, if there is residual photoresist 370', a residual ITO ring 360' remains along the inner foot of the opening 352 of the passivation structure 350 as shown in FIG. 4F. Even if the residual ITO ring 360' extends to contact the ITO wiring 363 due to photoresist residue 370', the enclosed opening 352 of the passivation structure 350 isolates the inner ITO wiring from ~~connected~~ connecting with any conductive layer outside the passivation structure 350, thereby preventing ITO wiring shorting with outside conductive layers. As well, the inner each ITO wiring is isolated from connected with any conductive layer outside the passivation structure by surrounding walls of the passivation structure.